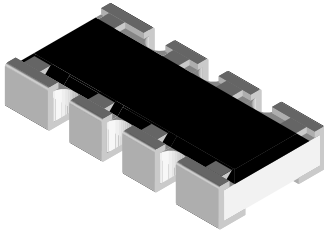




**THE DATASHEET OF
ACASA100121001P100**



Professional Thin Film Chip Resistor Array



The ACAS 0612 thin film chip resistor arrays combine the proven reliability of professional thin film chip resistor products with the advantages of chip resistor arrays. A small package enables the design of high density circuits in combination with reduction of assembly costs. Four equal resistor values or two pairs are available.

FEATURES

- Advanced thin film technology
- Two pairs or four equal resistor values
- TCR down to ± 25 ppm/K
- Tolerance down to ± 0.5 %
- Pure Sn termination on Ni barrier layer
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

APPLICATIONS

- Voltage divider
- Feedback circuits
- Signal conditioning

TECHNICAL SPECIFICATIONS	
DESCRIPTION	ACAS 0612
EIA size	0612
Metric size	RR1632M
Configuration, isolated	4 x 0603
Design:	
All equal	AE
Two pairs	TP
Resistance values	47 Ω to 221 k Ω ⁽¹⁾
Absolute tolerance ⁽²⁾	± 1 %; ± 0.5 %
Absolute temperature coefficient ⁽²⁾	± 50 ppm/K; ± 25 ppm/K
Max. resistance ratio R_{min}/R_{max} .	1:10
Rated dissipation: P_{70}	
Element	0.1 W
Package, 4 x 0603	0.3 W
Operating voltage	75 V
Permissible film temperature	125 °C
Operating temperature range	- 55 °C to 125 °C
Insulation voltage (U_{ins}) against ambient and between isolated resistors, continuous	75 V

Notes

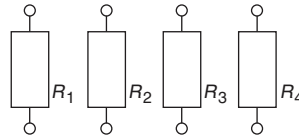
⁽¹⁾ Resistance values to be selected from E24; E192.

⁽²⁾ For specified TCR tracking, tolerance matching and even tighter absolute tolerance and TCR please refer to data sheet ACAS 0612 - Precision available on our web site at www.vishay.com/doc?28751.

APPLICATION INFORMATION

The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature is not exceeded. These resistors do not feature a limited lifetime when operated within the permissible limits.

CIRCUITS



ACAS 0612

DESIGN	
	ACAS 0612
AE	$R_1 = R_2 = R_3 = R_4$
TP	$R_1 = R_4 < R_2 = R_3$

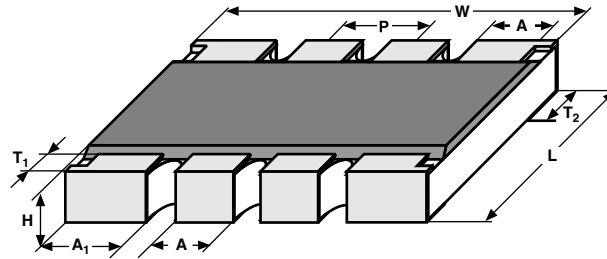
PART NUMBER AND PRODUCT DESCRIPTION																		
Part Number: ACASA110012200P500																		
A	C	A	S	A	1	1	0	0	1	2	2	0	0	P	5	0	0	
MODEL/ SIZE	TERMINAL	SIZE	RESISTANCE ⁽¹⁾	ACCURACY GRADE ⁽²⁾	RESISTANCE ⁽¹⁾	PACKAGING	SPECIAL											
ACA	S = Convex square	A = 0612	3 digit resistance value R_1, R_4 1 digit multiplier	TCR and tolerance 1 2 3	3 digit resistance value R_2, R_3 1 digit multiplier	P1 P5	00 = Standard											
			MULTIPLIER 9 = $\cdot 10^{-1}$ 0 = $\cdot 10^0$ 1 = $\cdot 10^1$ 2 = $\cdot 10^2$ 3 = $\cdot 10^3$															
			MULTIPLIER 9 = $\cdot 10^{-1}$ 0 = $\cdot 10^0$ 1 = $\cdot 10^1$ 2 = $\cdot 10^2$ 3 = $\cdot 10^3$															
Product Description: ACAS 0612 110R 1 220R P5																		
ACA	S	0612	110R	1	220R	P5												
MODEL/SIZE	TERMINATION	SIZE	RESISTANCE R_1, R_4 ⁽¹⁾	ACCURACY GRADE ⁽²⁾	RESISTANCE R_2, R_3 ⁽¹⁾	PACKAGING												
ACA = Chip Array	S = Convex square	0612	110R = 110 Ω 1K1 = 1.1 k Ω 22K1 = 22.1 k Ω	TCR and tolerance 1 2 3	220R = 220 Ω 1K1 = 1.1 k Ω 22K1 = 22.1 k Ω	P1 P5												

Notes

- Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION.
- ⁽¹⁾ $R_1 = R_4 \leq R_2 = R_3$.
- ⁽²⁾ Please refer to the table TEMPERATURE COEFFICIENT AND RESISTANCE RANGE, see next page.
- ⁽³⁾ Please refer to the table PACKAGING, see next page.

TEMPERATURE COEFFICIENT AND RESISTANCE RANGE						
TYPE	ACCURACY GRADE	ABSOLUTE		RELATIVE		RESISTANCE VALUE
		TCR	TOLERANCE	TCR	TOLERANCE	
ACAS 0612	1	± 25 ppm/K	± 0.5 %	-	-	47 Ω to 221 k Ω
	2	± 50 ppm/K	± 0.5 %	-	-	47 Ω to 221 k Ω
	3	± 50 ppm/K	± 1 %	-	-	47 Ω to 221 k Ω

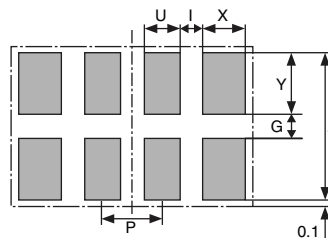
PACKAGING						
TYPE	CODE	QUANTITY	PACKAGING STYLE	WIDTH	PITCH	REEL DIAMETER
ACAS 0612	P1	1000	Tape and reel cardboard tape acc. IEC 60286-3 Type I	8 mm	4 mm	180 mm/7"
	P5	5000				

DIMENSIONS


DIMENSIONS - Chip resistor array, mass and relevant physical dimensions									
TYPE	L (mm)	W (mm)	H (mm)	P (mm)	A ₁ (mm)	A (mm)	T ₁ (mm)	T ₂ (mm)	MASS (mg)
ACAS 0612	1.5 \pm 0.15	3.2 \pm 0.15	0.45 \pm 0.1	0.8 \pm 0.1	0.6 \pm 0.1	0.4 \pm 0.1	0.3 \pm 0.15	0.4 \pm 0.15	6.6

PATTERN STYLES FOR CHIP RESISTOR ARRAY

ACAS 0612


 Dimensions in mm
 limits for solder resist

RECOMMENDED SOLDER PAD DIMENSIONS FOR CHIP RESISTOR ARRAYS							
TYPE	G (mm)	Y (mm)	X (mm)	U (mm)	Z (mm)	I (mm)	P (mm)
ACAS 0612	0.7	0.7	0.64	0.5	2.1	0.3	0.8



DESCRIPTION

The production of the components is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade (Al₂O₃) ceramic substrate using a mask to separate the adjacent resistors and conditioned to achieve the desired temperature coefficient. Specially designed inner contacts are realized on both sides. A special laser is used to achieve the target value by smoothly cutting a meander groove in the resistive layer without damaging the ceramics.

The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating.

The result of the determined production is verified by an extensive testing procedure and optical inspection performed on 100 % of the individual chip resistors. Only accepted products are laid directly into the paper tape in accordance with **IEC 60286-3** ⁽³⁾.

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using reflow or vapour phase as shown in **IEC 61760-1** ⁽³⁾. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system. The resistors are RoHS compliant; the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. The permitted storage time is 20 years, whereas the solderability is specified for 2 years after production or requalification. The immunity of the plating against tin whisker growth has been proven under extensive testing.

All products comply with the **GADSL** ⁽¹⁾ and the **CEFIC-EECA-EICTA** ⁽²⁾ list of legal restrictions on hazardous substances. This includes full compliance with the following directives:

- 2000/53/EC End of Vehicle life Directive (ELV) and Annex II (ELV II)
- 2011/65/EC Restriction of the use of Hazardous Substances directive (RoHS)
- 2002/96/EC Waste Electrical and Electronic Equipment Directive (WEEE)

TESTS

Where applicable, the resistors are tested in accordance with **EN 140401-801** which refers to **EN 60115-1** and **EN 140400**.

Notes

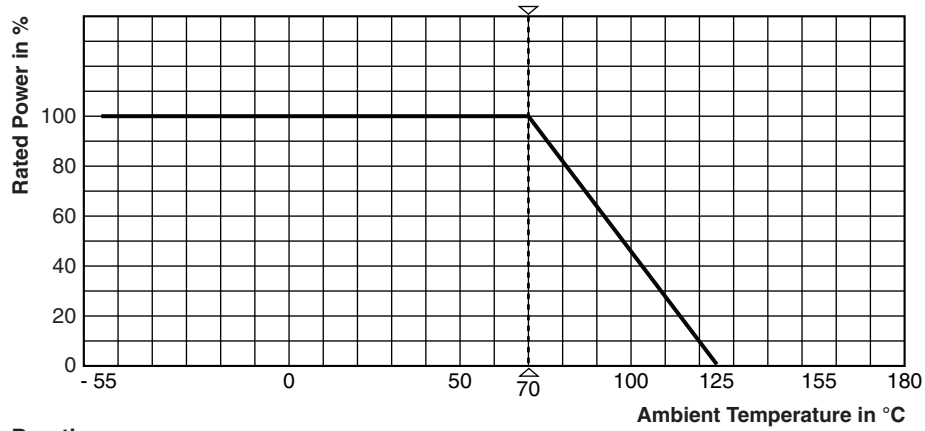
⁽¹⁾ Global Automotive Declarable Substance List, see www.gadsl.org.

⁽²⁾ CEFIC (European Chemical Industry Council), EECA (European Electronic Component Manufacturers Association), EICTA (European trade organisation representing the information and communications technology and consumer electronics), see www.eicta.org → policy → environmental policy group → chemicals → jig → Joint Industry Guide (JIG-101 Ed 2.0).

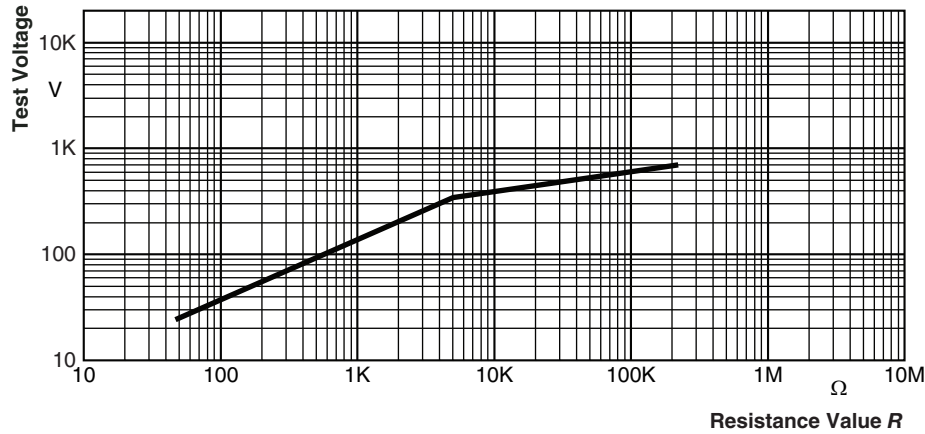
⁽³⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents.



FUNCTIONAL PERFORMANCE

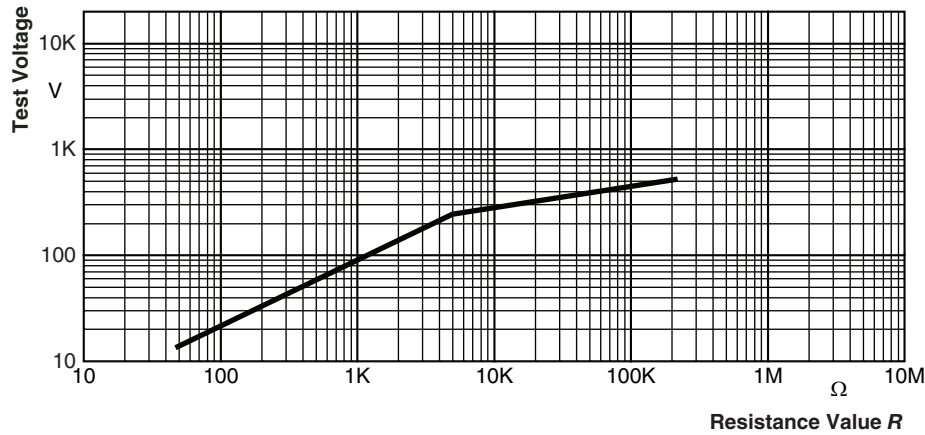


Derating



Pulse load rating for arrays with equal values, design type AE, in accordance with EN 60115-1 clause 4.27; 1.2 μs/50 μs; 5 pulses at 12 s interval; for permissible resistance change (0.5 % R + 0.05 Ω)

1.2/50 Pulse



Pulse load rating rating for arrays with equal values, design type AE in accordance with EN 60115-1 clause 4.27; 10 μs/700 μs; 10 pulses at 1 min intervals; for permissible resistance change (0.5 % R + 0.05 Ω)

10/700 Pulse



TESTS AND REQUIREMENTS

Essentially all tests are carried out in accordance with the following specifications:

EN 60115-1, generic specification

EN 140400, sectional specification

EN 140401-801, detail specification

The testing also covers most of the requirements specified by EIA/IS-703 and JIS-C-5202.

The tests are carried out in accordance with **IEC 60068 (1)** and under standard atmospheric conditions according to **IEC 60068-1 (1)**, 5.3. Climatic category LCT/UCT/56 (rated

temperature range: Lower category temperature, upper category temperature; damp heat, long term, 56 days) is valid (LCT = - 55 °C/UCT = 125 °C).

Unless otherwise specified the following values apply:

Temperature: 15 °C to 35 °C

Relative humidity: 45 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar)

The requirements stated in the “Test Procedures and Requirements” table are based on the required tests and permitted limits of EN 140401-801 where applicable.

TEST PROCEDURES AND REQUIREMENTS				
EN 60115-1 CLAUSE	IEC 60068-2 (1) TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (2) (ΔR)
			Stability for product types: ACAS 0612	47 Ω to 221 kΩ
4.5	-	Resistance	-	± 1 %; ± 0.5 %
4.8.4.2	-	Temperature coefficient	At (20/- 55/20) °C and (20/125/20) °C	± 50 ppm/K; ± 25 ppm/K
4.25.1	-	Endurance	$U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$; 1.5 h on; 0.5 h off; whichever is the less severe; 70 °C; 1000 h	± (0.25 % R + 0.05 Ω)
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h	± (0.25 % R + 0.05 Ω)
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (0.5 % R + 0.05 Ω)
4.13	-	Short time overload (3)	$U = 2.5 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{max.}$; 5 s	± (0.1 % R + 0.01 Ω) no visible damage
4.19	14 (Na)	Rapid change of temperature	30 min at - 55 °C and 30 min at 125 °C; 5 cycles	± (0.1 % R + 0.01 Ω) no visible damage
4.18.2	58 (Td)	Resistance to soldering heat	Reflow method 2 (IR/forced gas convection); (260 ± 5) °C; (10 ± 1) s	± (0.25 % R + 0.01 Ω) no visible damage
4.17.2	58 (Td)	Solderability	Solder bath method; SnPb; non-activated flux accelerated ageing 4 h/155 °C (215 ± 3) °C; (3 ± 0.3) s	Good tinning (≥ 95 % covered); no visible damage
			Solder bath method; SnAgCu; non-activated flux accelerated ageing 4 h/155 °C (235 ± 3) °C; (2 ± 0.2) s	
4.32	21 (Ue3)	Shear (adhesion)	45 N	No visible damage
4.33	21 (Ue1)	Substrate bending	Depth 2 mm, 3 times	± (0.1 % R + 0.01 Ω) no visible damage; no open circuit in bent position
4.7	-	Voltage proof	$U_{RMS} = U_{ins}$ (60 ± 5) s; against ambient, between adjacent resistors	No flashover or breakdown

Notes

(1) The quoted IEC standards are also released as EN standards with the same number and identical contents.

(2) Figures are given for arrays with equal values, design type AE.

(3) For a single element.



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View ACASA100121001P100 on WIN SOURCE](#)

 [Vishay Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management